

**Tender of
RMB-denominated 2.41 per cent. Bonds due 2023 (the “Additional 2023 Bonds”) (to be consolidated and form a single series with the RMB5 billion 2.41 per cent. Bonds due 2023 (the “Original 2023 Bonds”))**

and

RMB-denominated 3.60 per cent. Bonds due 2028 (the “Additional 2028 Bonds”) (to be consolidated and form a single series with the RMB0.5 billion 3.60 per cent. Bonds due 2028 (the “Original 2028 Bonds”))

To be held on 20 October 2021

The Ministry of Finance of the People’s Republic of China (the “**Ministry of Finance**”) announces that a tender of the Additional 2023 Bonds and the Additional 2028 Bonds (together, the “**Additional Bonds**”) of the Central People’s Government will be held on Wednesday, 20 October 2021, for settlement on Friday, 22 October 2021.

A total of RMB4.5 billion Additional 2023 Bonds and RMB1.5 billion Additional 2028 Bonds will be made available for competitive tender on a price-bid basis by any qualified Central Moneymarkets Unit (“**CMU**”) members through the CMU BID. Upon issuance, the Additional 2023 Bonds will be consolidated and form a single series with the Original 2023 Bonds (the “**2023 Bonds**”) and the Additional 2028 Bonds will be consolidated and form a single series with the Original 2028 Bonds (the “**2028 Bonds**”, together with the 2023 Bonds, the “**Bonds**”). The 2023 Bonds bear interest at 2.41 per cent. per annum. The 2028 Bonds bear interest at 3.60 per cent. per annum. The 2023 Bonds and the 2028 Bonds will mature in 2023 and 2028, respectively, on the last interest payment date of the relevant series of Bonds. Each series of Additional Bonds will be issued at the uniform issue price i.e. the lowest accepted price of the successful competitive tender bids for the relevant series, plus accrued interest.

Each tender must be for an amount of RMB500,000 or integral multiples thereof and the difference between any specified tender price should be at least 0.01%, rounded to two decimal places.

The tender results will be published on the website of the Hong Kong Monetary Authority (“**HKMA**”) (<https://www.hkma.gov.hk>) and the CMU Bond Price Bulletin (<https://www.cmu.org.hk>).

The Tender Information Memorandum of the Ministry of Finance dated 13 October 2021 includes the details of the tender of the Additional Bonds, including the terms of the Bonds, the tender arrangements and the application, payment and settlement procedures. Copies of the Tender Information Memorandum can be obtained from the HKMA at 55/F, Two International Finance Centre, 8 Finance Street, Central, Hong Kong (Tel: 8100 0136) or from the Issuing and Lodging Agent, Bank of Communications Co., Ltd, Hong Kong Branch at 20 Pedder Street, Central, Hong Kong (Tel: 2315 7386 / 2315 7387). It can also be downloaded from the respective websites of the HKMA and the Issuing and Lodging Agent at <https://www.bankcomm.com.hk>.

The Ministry of Finance will tender the Additional Bonds through the CMU BID. The tender and settlement of the Additional Bonds will be governed by the Tender Information Memorandum and the Applicable Terms and Conditions of CMU BID issued by the HKMA as the system administrator and service provider of the CMU BID, as amended from time to time, the CMU Operating Procedures and other relevant CMU rules (subject to any amendments under the Tender Information Memorandum).

The Ministry of Finance has appointed Bank of Communications Co., Ltd. Hong Kong Branch as the Issuing and Lodging Agent to administer the tender of the Additional Bonds on its behalf.

The Ministry of Finance of the People's Republic of China

13 October 2021

Bonds Tender Information

Information of each series of Additional Bonds:

CMU Instrument No.	:	2023 Bonds	:	BCMFKFB21002
		2028 Bonds	:	BCMFKFB13045
Tender Date and Time	:	Wednesday, 20 October 2021 9:30 a.m. to 10:30 a.m.		
Issue and Settlement Date	:	Friday, 22 October 2021		
Aggregate Principal Amount Tendered	:	Additional 2023 Bonds	:	RMB4.5 billion
		Additional 2028 Bonds	:	RMB1.5 billion
Denomination	:	RMB500,000 each		
Issue Price	:	Each series of Additional Bonds will be issued at the lowest accepted price of the successful competitive tender bids for the relevant series, plus accrued interest		
Maturity Date	:	Last interest payment date of the relevant series of Bonds in 2023 and 2028, respectively		
Interest Rates and Accrued Interest	:	The 2023 Bonds bear interest at 2.41 per cent. per annum and the accrued interest on each 2023 Bond from and including 27 September 2021 up to but excluding the Further Issue Date is RMB825.34		
		The 2028 Bonds bear interest at 3.60 per cent. per annum and the accrued interest on each 2028 Bond from and including 28 June 2021 up to but excluding the Further Issue Date is RMB5,720.55		
Interest Payment Dates	:	In respect of the 2023 Bonds: 27 March and 27 September in each year, subject to the modified following business day convention In respect of the 2028 Bonds: 27 June and 27 December in each year, subject to the modified following business day convention		
Tender Amount	:	RMB500,000 or integral multiples thereof and the difference between any specified tender prices should be at least 0.01%, rounded to two decimal places		
Other details	:	Please refer to the Tender Information Memorandum		

The Ministry of Finance of the People's Republic of China

13 October 2021

Note: This Tender Notice is published in Chinese and English. The English version is intended for ease of reference only. In the event of any inconsistency between the Chinese version and English version of this Tender Notice, the Chinese version shall prevail.